

Finland-Espoo: Miscellaneous general and special-purpose machinery
OJ S 174/2023 11/09/2023
Contract award notice
Supplies

Legal Basis:

Directive 2014/24/EU

Section I: Contracting authority

I.1. Name and addresses

Official name: VTT Technical Research Centre of Finland Ltd

National registration number: 2647375-4

Postal address: P.O. Box 1000, VTT

Town: Espoo

NUTS code: FI1 Manner-Suomi

Postal code: 02044

Country: Finland

E-mail: kilpailutus@vtt.fi

Telephone: +358 20722111

Internet address(es):

Main address: <https://www.vttresearch.com/en>

I.4. Type of the contracting authority

Body governed by public law

I.5. Main activity

Other activity: Research and development

Section II: Object

II.1. Scope of the procurement

II.1.1. Title

AUTOMATIC WAFER GRINDER

Reference number: Reg.no. 24/206/2023

II.1.2. Main CPV code

42900000 Miscellaneous general and special-purpose machinery

II.1.3. Type of contract

Supplies

II.1.4. Short description

The object of the tender was an Automatic Wafer Grinder, capable of thinning Si and SiC, LiNbO₃ wafers of 100, 150 and 200mm diameter to varying thicknesses with end-point control, cassette-to-cassette processing, TTV profile control and capability to handle thin wafers 100um thick supported by tape and grind away bonded wafer stacks to within 3 um of a typical interface.

The object of the tender process was described in more detail in the invitation to tender documents.

II.1.6. Information about lots

This contract is divided into lots: no

II.1.7. Total value of the procurement

Value excluding VAT: 739 030,00 EUR

II.2. Description

II.2.3. Place of performance

NUTS code: FI1 Manner-Suomi

II.2.4. Description of the procurement

The object of the tender was an Automatic Wafer Grinder (later also "Equipment"), capable of thinning Si and SiC, LiNbO3 wafers of 100, 150 and 200mm diameter to varying thicknesses with end-point control, cassette-to-cassette processing, TTV profile control and capability to handle thin wafers 100um thick supported by tape and grind away bonded wafer stacks to within 3 um of a typical interface.

The technical specification of the equipment to be supplied was discussed in more detail in Annex 1.

The objective was to find one professional supplier that can guarantee a high standard of quality and who is capable of providing the Automatic Wafer Grinder, installation, and user training in its entirety. VTT Technical Research Centre of Finland Ltd will choose one supplier from among the tenderers.

II.2.5. Award criteria

Quality criterion - Name: Quality / Weighting: 0

Price - Weighting: 100

II.2.11. Information about options

Options: no

II.2.13. Information about European Union funds

The procurement is related to a project and/or programme financed by European Union funds: no

II.2.14. Additional information

Section IV: Procedure

IV.1. Description

IV.1.1. Type of procedure

Open procedure

IV.1.3. Information about a framework agreement or a dynamic purchasing system

IV.1.8. Information about the Government Procurement Agreement (GPA)

The procurement is covered by the Government Procurement Agreement: yes

IV.2. Administrative information

IV.2.1. Previous publication concerning this procedure

Notice number in the OJ S: [2023/S 070-210605](#)

IV.2.8. Information about termination of dynamic purchasing system

IV.2.9. Information about termination of call for competition in the form of a prior information notice

Section V: Award of contract

Title:

AUTOMATIC WAFER GRINDER

A contract/lot is awarded: yes

V.2. Award of contract

V.2.1. Date of conclusion of the contract

19/06/2023

V.2.2. Information about tenders

Number of tenders received: 1

Number of tenders received from SMEs: 0

Number of tenders received by electronic means: 1

The contract has been awarded to a group of economic operators: no

V.2.3. Name and address of the contractor

Official name: DISCO HI-TEC EUROPE GmbH

National registration number: DE131174016

Town: München

NUTS code: DE Deutschland

Country: Germany

The contractor is an SME: no

V.2.4. Information on value of the contract/lot

Total value of the contract/lot: 739 030,00 EUR

V.2.5. Information about subcontracting

Section VI: Complementary information

VI.3. Additional information

VI.4. Procedures for review

VI.4.1. Review body

Official name: Markkinaoikeus

Postal address: Sörnäistenkatu 1

Town: Helsinki

Postal code: 00580

Country: Finland

E-mail: markkinaoikeus@oikeus.fi

Telephone: +358 295643300

Internet address: <http://www.oikeus.fi/markkinaoikeus>

VI.5. Date of dispatch of this notice

06/09/2023